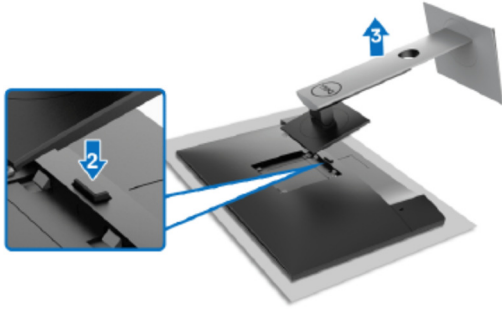


1. Disassembly Procedures

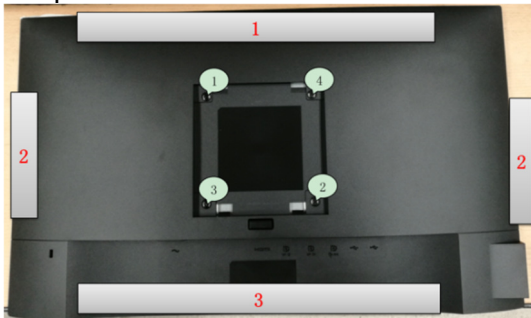
S1 Turn off power

S2 Place the monitor on a soft cloth or cushion.
Press and hold the stand-release button.
Lift the stand up and away from the monitor.



S3 Unlock 4 Rear Cover screws.

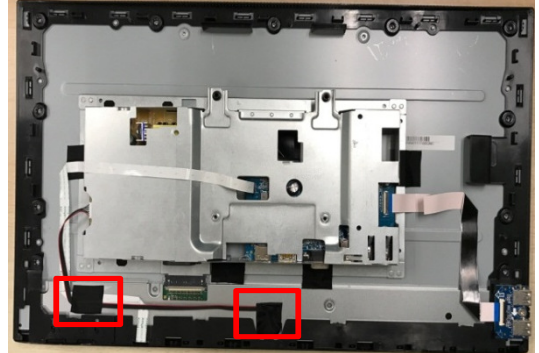
Disassemble Rear Cover and Middle Frame according to the sequence as the picture showed



(Screw Torque: 9±1Kgf)



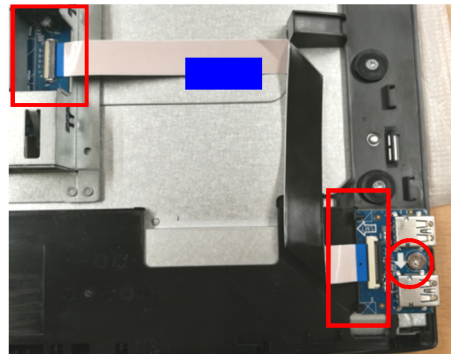
S4 Tear off 2 adhesive tapes
Pull out lamp cable



S5 Pull out USB board cable from USB Board and I/F Board

Unlock a screw on USB Board

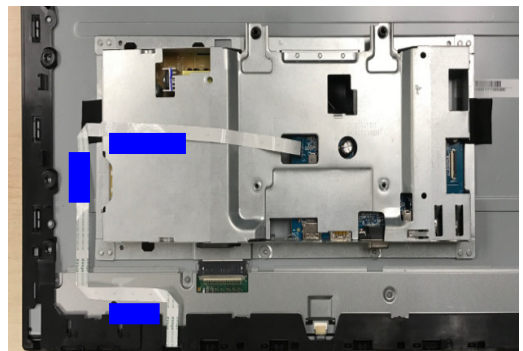
Disassemble the USB Board from Middle Frame



(Screw Torque: 4.5±0.5Kgf)

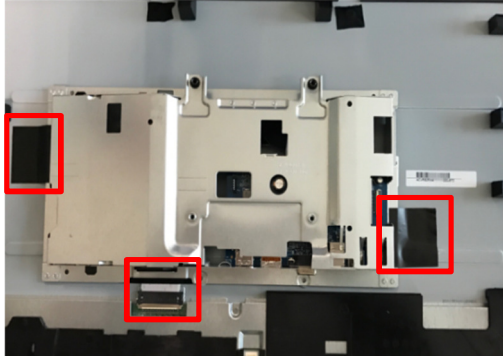
S6 Extract Control Board FFC cable from I/F Board

Tear off Control Board FFC cable from Main Shielding



S7 Tear off tapes to disassemble Main Shielding

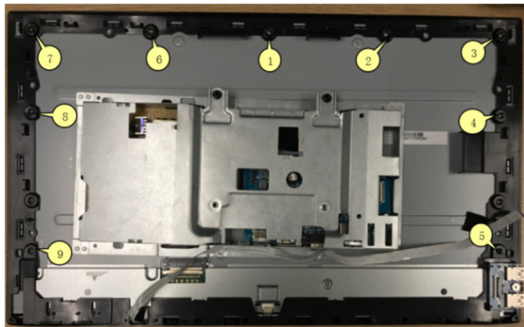
Pull out LVDS cable and take off Main Shielding



S10 Disassemble Middle Frame and Bezel



S8 Unlock 9 screws on Middle Frame

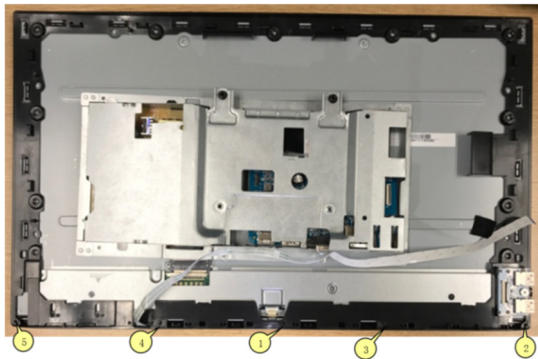


(Screw Torque: 3.5~4.0Kgf)

S11 Disassemble Mylar from Main Shielding

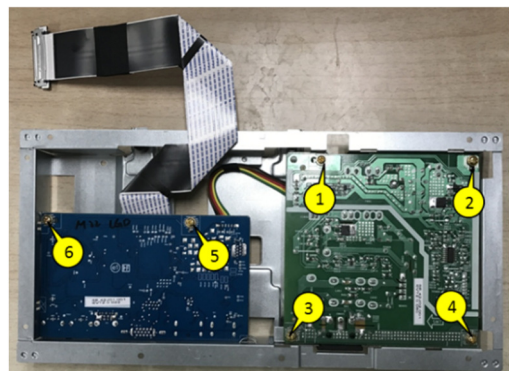


S9 Unlock 5 screws on Bezel



(Screw Torque: 1.25-1.3kgf)

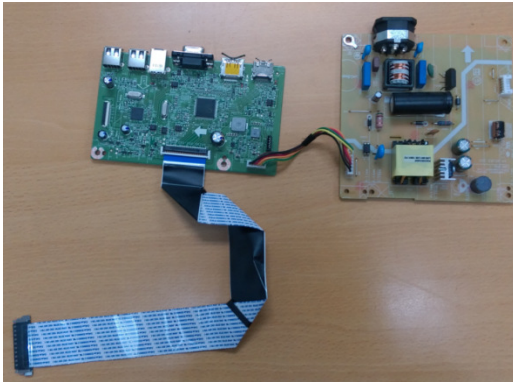
S12 Unlock 6 PCB screws and 2 hex screws



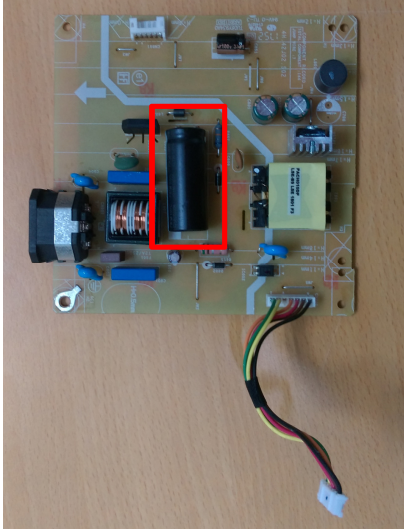
(Screw Torque for PCB screw: 8~9kgf)
(Screw Torque for Hex screw: 5±0.6kgf)

- S13** Take out I/F Board and SPS Board from Main Shielding

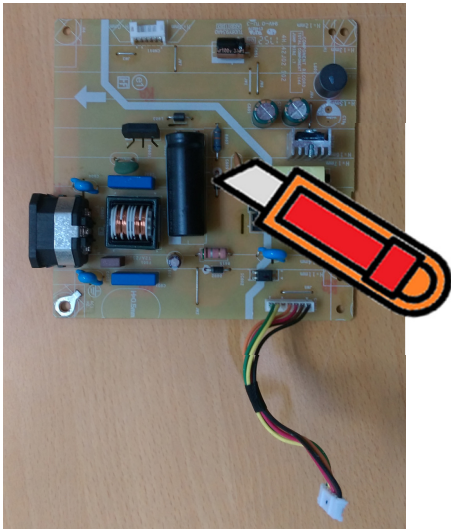
Pull out LVDS cable and SPS board cable from I/F Board



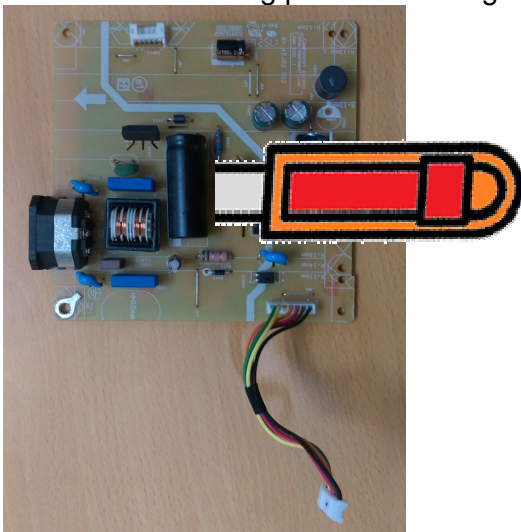
S14 Remove electrolyte capacitors (red mark) from printed circuit boards



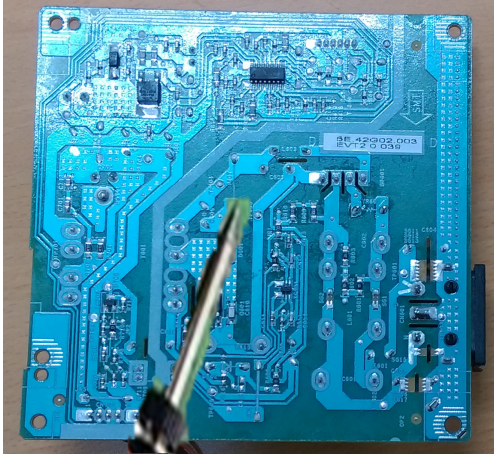
S14-1 Cut the glue between bulk cap. and PCB with a knife



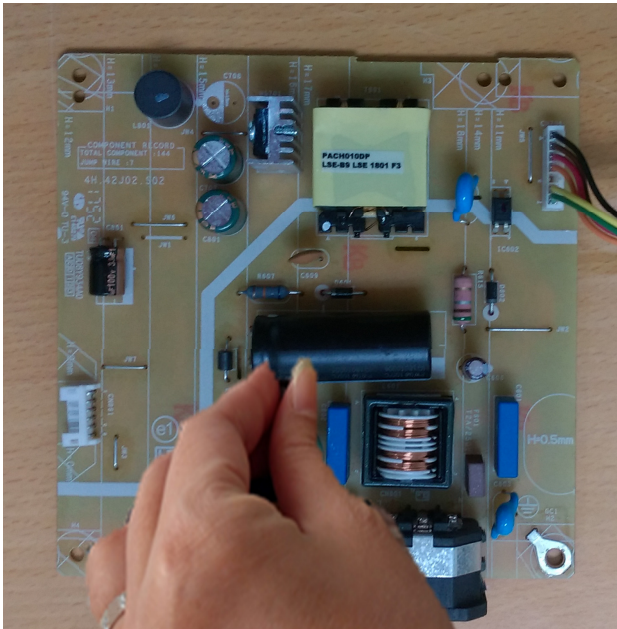
S14-2 Ensure cutting path within the glue, don't touch bulk cap. or PCB



S14-3 Take out bulk cap. pin solder with soldering iron and absorber



S14-4 Lift the bulk cap. up and away from the PCB



2. Product material information

The following substances, preparations, or components should be disposed of or recovered separately from other WEEE in compliance with Article 4 of EU Council Directive 75/442/EEC.

Capacitors / condensers (containing PCB/PCT)	No used
Mercury containing components	No used
Batteries	No used
Printed circuit boards (with a surface greater than 10 square cm)	Product has printed circuit boards (with a surface greater than 10 square cm)
Component contain toner, ink and liquids	No used
Plastic containing BFR	No used
Component and waste contain asbestos	No used
CRT	No used
Component contain CFC, HCFC, HFC and HC	No used
Gas discharge lamps	No used
LCD display > 100 cm ²	Product has an LCD greater than 100 cm ²
External electric cable	Product has external cables
Component contain refractory ceramic fibers	No used
Component contain radio-active substances	No used
Electrolyte capacitors (height > 25mm, diameter > 25mm)	Product has electrolyte capacitors (height >25mm, diameter > 25mm)

3. Tools Required

List the type and size of the tools that would typically can be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description:

- Screwdriver
- Penknife
- Bar scraper